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54 **Electrolytic copper plating.**

57 A copper plating bath, for example  $\text{CuSO}_4 + \text{H}_2\text{SO}_4$ , further containing a sulfur-containing anion other than sulfate anion, and/or a selenium-containing anion other than a selenate anion, and/or a tellurium-containing anion other than a tellurate anion, in an amount sufficient to increase the plating rate, and method for electroplating copper onto a substrate with the plating bath.



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# EUROPEAN SEARCH REPORT

**0142831**

Application number

EP 84 11 3862

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl. 4)
X	CHEMICAL ABSTRACTS, vol. 84, no. 22, 31st May 1976, page 468, no. 157135e, Columbus, Ohio, US; T.I. CEZHAVA et al.: "Effect of anions of some oxy acids on copper electroplating" & SOOBESHCH. AKAD. NAUK GRUZ. SSR 1976, 81(1), 113-116	1-3, 7, 8, 10	C 25 D 3/38
A	<p style="text-align: center;">---</p> US-A-4 347 108 (WILLIS) * Column 8, lines 64-68 * <p style="text-align: center;">-----</p>	4-6	TECHNICAL FIELDS SEARCHED (Int. Cl. 4)  C 25 D 3/38
The present search report has been drawn up for all claims			
Place of search <b>THE HAGUE</b>		Date of completion of the search <b>19-04-1985</b>	Examiner <b>VAN LEEUWEN R.H.</b>
<b>CATEGORY OF CITED DOCUMENTS</b> X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			